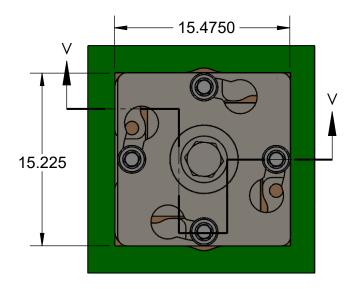
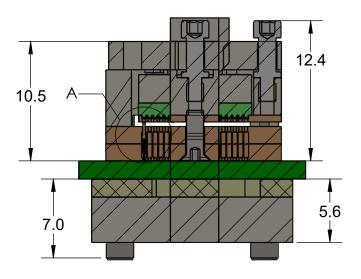
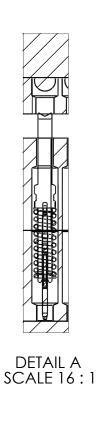
SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR **BURN-IN AND TEST APPLICATIONS**

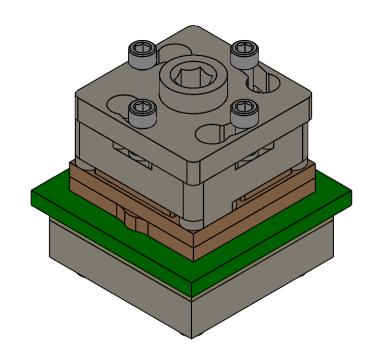




Features:

- Wide temperature range (-55C to +180C)
 High current capability (up to 4A)
 Excellent signal integrity at high frequencies
 Low and stable contact resistance for reliable production yield
 Highly compliant to accommodate wide co-planarity variations
 Automated probe manufacturing enables low cost and short lead time





Description: SBT-BGATION 9/10mmx10mm 0.5mm pitch

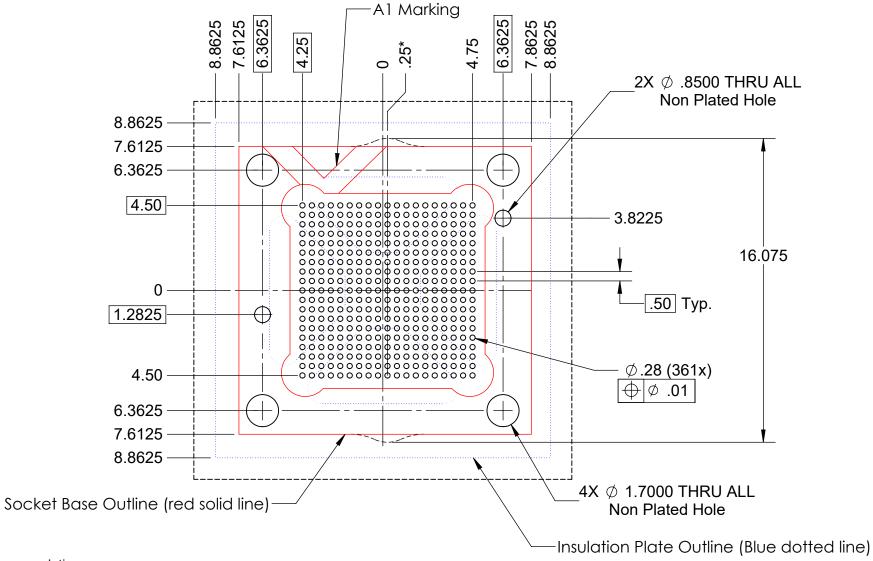
Primary dimension units are millimeters, Secondary dimension units are [inches]. Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SBT	-BGA-7004 Specification
	Ironwood Flectronics Inc

Tele: (800) 404-0204 www.ironwoodélectronics.com Material: Material <not specified>

Finish: Weight: 10.88

STATUS: Released	SHEET: 1 OF 4	REV. A
DRAWN BY: B. Schatz	SCALE: 3:1	
FILE: SBT-BGA-7004	DATE: 8/16/2013	



*BGA pattern is offset 0.25mm

with respect to the mounting holes. 0

NOTES:

1. Target PCB Recommendations

2. Total thickness: 1.6mm min.

3. Plating: Gold or Solder finish

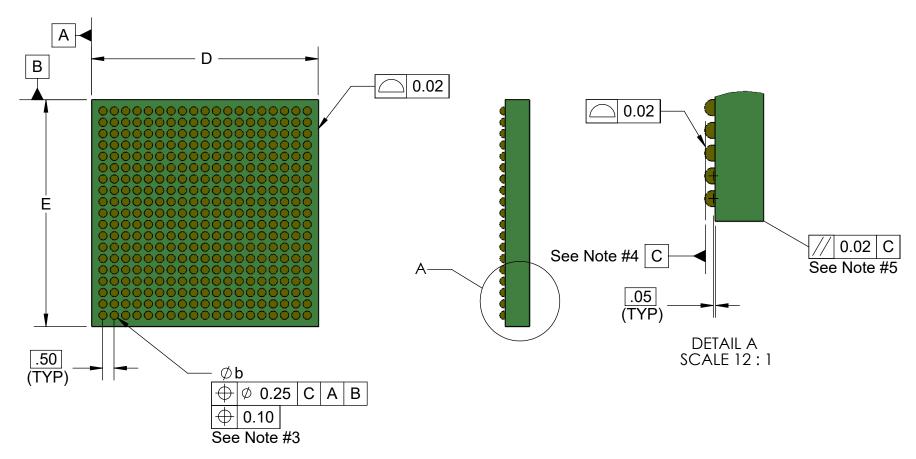
4. PCB Pad height: Same or higher than solder mask

Description: Recommended Layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±

SBT-BGA-7004 Drawing	Material: Material <not specified=""></not>	STATUS: Released	SHEET: 2 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204	Finish: Weight: 10.88	DRAWN BY: B. Schatz	SCALE: 5:1	
www.ironwoodelectronics.com		FILE: SBT-BGA-7004	DATE: 8/16/2013	



NOTES:

- 1. Dimensions are in millimeters.
- 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

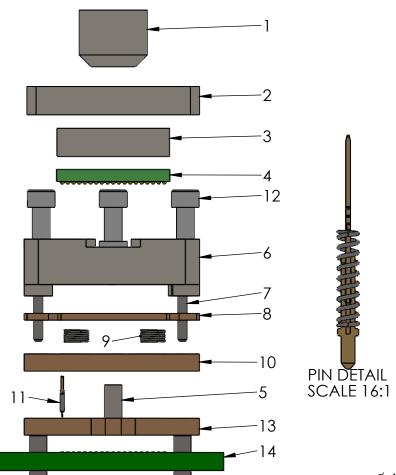
DIM	Minimum	Maximum
Α		1.2
b		0.35
D	10.0 BSC	
E	10.0 BSC	

Description: BGA Spec

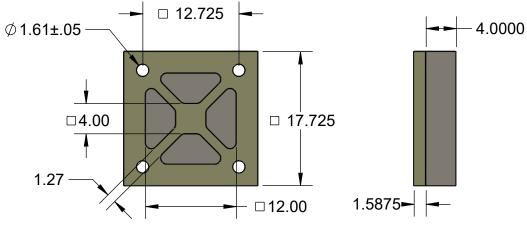
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

<u>Tolerances:</u> Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], Pitches (from true position) ±0.025mm

	SBT-BGA-7004 Drawing	Material: Material <not specified=""></not>	STATUS: Released	SHEET: 3 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: Weight: 10.88	DRAWN BY: B. Schatz	SCALE: 2:1		
	. \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	Weight. 10.00	FILE: SBT-BGA-7004	DATE: 8/16/2013	



TELL		
ITEM NO.	Description	Material
1	Compression Screw M6x1	Stainless Steel (18-8)
2	Socket Lid	7075-T6 Aluminum Alloy
3	Compression Plate	7075-T6 Aluminum Alloy
4	Test Chip	
5	#0-80, 90 deg., head pin guide screw, Peek material	PEEK unfilled
6	Socket Base SBT BGA 10x10	7075-T6 Alumium Alloy
7	Dowel pin, 1/32" X 1/4", SS	Stainless Steel (18-8)
8	Floating Guide SBT-BGA 10x10mm, 0.5mm pitch 19x19 array	Semitron MDS 100
9	Floating Guide Spring	Alloy Steel (SS)
10	SBT-BGA Middle Guide 10x10mm, 0.5mm pitch, 19x19 array	Semitron MDS 100
11	SBT Pin, SBT-BGA 0.5mm-0.8mm #0-80 Shoulder Screw, 1.59mm thread	
12	length	Stainless Steel (303)
13	SBT-BGA Bottom guide 10x10mm, 0.5mm Pitch, 19x19 array	Semitron MDS 100
14	Target PCB	
15	Insulation Plate	FR4 High temp
16	SBT/CBT Ni plt backing plate 13mm	7075-T6 Aluminum Alloy
17	#0-80 x 0.5, SH Cap Screw	Alloy Steel



Description: Socket Assy, Insulation Plate

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

<u>Tolerances:</u> Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SB	Γ-BGA-7004 Drawing
A	Ironwood Electronics, Tele: (800) 404-020 www.ironwoodelectronic
•	www.ironwoodélectronic

Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com

Material: Material <not specified>

Finish:

ı illiəli.	
Weight:	10.88

STATUS: Released	SHEET: 4 OF 4 REV. A
DRAWN BY: B. Schatz	SCALE: 3:1
FILE: SBT-BGA-7004	DATE: 8/16/2013